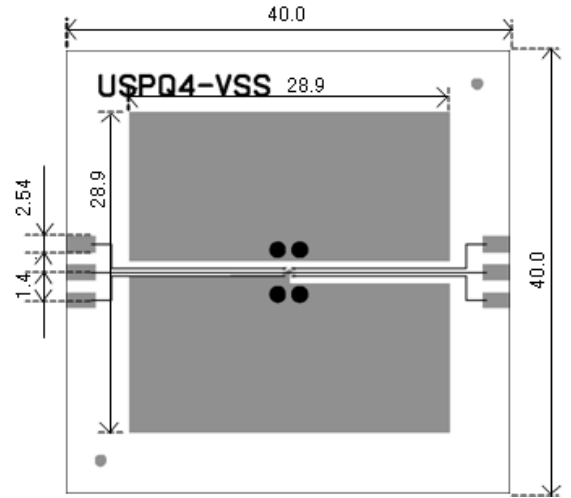


● USPQ-4B04 Power Dissipation

Power dissipation data for the USPQ-4B04 is shown in this page.  
 The value of power dissipation varies with the mount board conditions.  
 Please use this data as the reference data taken in the following condition.

1. Measurement Condition

- Condition : Mount on a board
- Ambient : Natural convection
- Soldering : Lead (Pb) free
- Board Dimensions : 40 x 40 mm (1600mm<sup>2</sup>)
- Board Structure : 4 Copper Layers  
 Each layer is connected to the package heat-sink and terminal pin No.1.  
 Each layer has approximately 800mm<sup>2</sup> copper area.
- Material : Glass Epoxy (FR-4)
- Thickness : 1.6 mm
- Through-hole : 4 x 0.8 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (T<sub>j</sub> max = 125°C)

Ambient Temperature(°C)	Power Dissipation Pd(mW)	Thermal Resistance (°C/W)
25	550	181.82
85	220	

